

## Molding Type Module IGBT, 2 in 1 Package, 1200 V, 100 A


**INT-A-PAK**
**FEATURES**

- High short circuit capability, self limiting to  $6 \times I_C$
- 10  $\mu$ s short circuit capability
- $V_{CE(on)}$  with positive temperature coefficient
- Maximum junction temperature 150 °C
- Low inductance case
- Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT

PRODUCT SUMMARY	
$V_{CES}$	1200 V
$I_C$ at $T_C = 80$ °C	100 A
$V_{CE(on)}$ (typical) at $I_C = 100$ A, 25 °C	1.80 V
Package	INT-A-PAK
Circuit	Half Bridge

**TYPICAL APPLICATIONS**

- AC inverter drives
- Switching mode power supplies
- Electronic welders

**DESCRIPTION**

Vishay's IGBT power module provides ultra low conduction loss as well as short circuit ruggedness. It is designed for applications such as general inverters and UPS.

ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C unless otherwise noted)				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	$V_{CES}$		1200	V
Gate to emitter voltage	$V_{GES}$		$\pm 20$	
Collector current	$I_C$	$T_C = 25$ °C	200	A
		$T_C = 80$ °C	100	
Pulsed collector current	$I_{CM}^{(1)}$	$t_p = 1$ ms	200	
Diode continuous forward current	$I_F$		100	
Diode maximum forward current	$I_{FM}$		200	
Maximum power dissipation	$P_D$	$T_J = 150$ °C	650	
Short circuit withstand time	$t_{SC}$	$T_J = 125$ °C	10	$\mu$ s
RMS isolation voltage	$V_{ISOL}$	$f = 50$ Hz, $t = 1$ min	2500	V
$I^2t$ -value, diode	$I^2t$	$V_R = 0$ V, $t = 10$ ms, $T_J = 125$ °C	1050	A <sup>2</sup> s

**Note**

<sup>(1)</sup> Repetitive rating: Pulse width limited by maximum junction temperature.



IGBT ELECTRICAL SPECIFICATIONS ( $T_C = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0\text{ V}, I_C = 1.0\text{ mA}, T_J = 25\text{ }^\circ\text{C}$	1200	-	-	V
Collector to emitter voltage	$V_{CE(on)}$	$V_{GE} = 15\text{ V}, I_C = 100\text{ A}, T_J = 25\text{ }^\circ\text{C}$	-	1.80	2.20	
		$V_{GE} = 15\text{ V}, I_C = 100\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	2.05	-	
Gate to emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}, I_C = 4.0\text{ mA}, T_J = 25\text{ }^\circ\text{C}$	5.0	6.2	7.0	
Collector cut-off current	$I_{CES}$	$V_{CE} = V_{CES}, V_{GE} = 0\text{ V}, T_J = 25\text{ }^\circ\text{C}$	-	-	5.0	mA
Gate to emitter leakage current	$I_{GES}$	$V_{GE} = V_{GES}, V_{CE} = 0\text{ V}, T_J = 25\text{ }^\circ\text{C}$	-	-	400	nA

SWITCHING CHARACTERISTICS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	$t_{d(on)}$	$V_{CC} = 600\text{ V}, I_C = 100\text{ A}, R_g = 5.6\text{ }\Omega, V_{GE} = \pm 15\text{ V}, T_J = 25\text{ }^\circ\text{C}$	-	279	-	ns
Rise time	$t_r$		-	61	-	
Turn-off delay time	$t_{d(off)}$		-	308	-	
Fall time	$t_f$		-	205	-	mJ
Turn-on switching loss	$E_{on}$		-	5.56	-	
Turn-off switching loss	$E_{off}$	-	6.95	-		
Turn-on delay time	$t_{d(on)}$	$V_{CC} = 600\text{ V}, I_C = 100\text{ A}, R_g = 5.6\text{ }\Omega, V_{GE} = \pm 15\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	287	-	ns
Rise time	$t_r$		-	63	-	
Turn-off delay time	$t_{d(off)}$		-	328	-	
Fall time	$t_f$		-	360	-	mJ
Turn-on switching loss	$E_{on}$		-	7.85	-	
Turn-off switching loss	$E_{off}$	-	10.55	-		
Input capacitance	$C_{ies}$	$V_{GE} = 0\text{ V}, V_{CE} = 25\text{ V}, f = 1.0\text{ MHz}, T_J = 25\text{ }^\circ\text{C}$	-	7.43	-	nF
Output capacitance	$C_{oes}$		-	0.52	-	
Reverse transfer capacitance	$C_{res}$		-	0.34	-	
SC data	$I_{SC}$	$t_{sc} \leq 10\text{ }\mu\text{s}, V_{GE} = 15\text{ V}, T_J = 125\text{ }^\circ\text{C}, V_{CC} = 900\text{ V}, V_{CEM} \leq 1200\text{ V}$	-	470	-	A
Internal gate resistance	$R_{gint}$		-	2	-	$\Omega$
Stray inductance	$L_{CE}$		-	-	30	nH
Module lead resistance, terminal to chip	$R_{CC'+EE'}$	$T_C = 25\text{ }^\circ\text{C}$	-	0.75	-	m $\Omega$

DIODE ELECTRICAL SPECIFICATIONS ( $T_C = 25\text{ }^\circ\text{C}$ unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Diode forward voltage	$V_F$	$I_F = 100\text{ A}$	$T_J = 25\text{ }^\circ\text{C}$	-	1.90	2.30	V
			$T_J = 125\text{ }^\circ\text{C}$	-	2.00	-	
Diode reverse recovery charge	$Q_{rr}$	$I_F = 100\text{ A}, V_R = 600\text{ V}, di_F/dt = -2000\text{ A}/\mu\text{s}, V_{GE} = -15\text{ V}$	$T_J = 25\text{ }^\circ\text{C}$	-	5.52	-	$\mu\text{C}$
			$T_J = 125\text{ }^\circ\text{C}$	-	11.88	-	
Diode peak reverse recovery current	$I_{rr}$	$I_F = 100\text{ A}, V_R = 600\text{ V}, di_F/dt = -2000\text{ A}/\mu\text{s}, V_{GE} = -15\text{ V}$	$T_J = 25\text{ }^\circ\text{C}$	-	85	-	A
			$T_J = 125\text{ }^\circ\text{C}$	-	103	-	
Diode reverse recovery energy	$E_{rec}$	$I_F = 100\text{ A}, V_R = 600\text{ V}, di_F/dt = -2000\text{ A}/\mu\text{s}, V_{GE} = -15\text{ V}$	$T_J = 25\text{ }^\circ\text{C}$	-	2.06	-	mJ
			$T_J = 125\text{ }^\circ\text{C}$	-	5.56	-	



THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Operating junction temperature	$T_J$		-	-	150	°C
Storage temperature range	$T_{STG}$		- 40	-	125	
Junction to case	$R_{thJC}$	IGBT (per 1/2 module)	-	-	0.19	K/W
		Diode (per 1/2 module)	-	-	0.28	
Case to sink	$R_{thCS}$	Conductive grease applied	-	0.05	-	
Mounting torque		Power terminal screw: M5	2.5 to 5.0			Nm
		Mounting screw: M6	3.0 to 5.0			
Weight of module			150			g

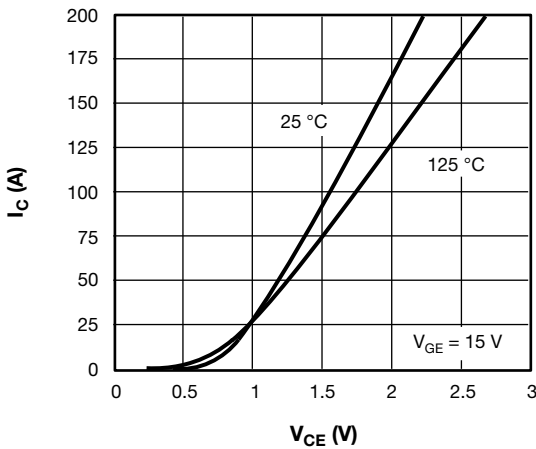


Fig. 1 - IGBT Typical Output Characteristics

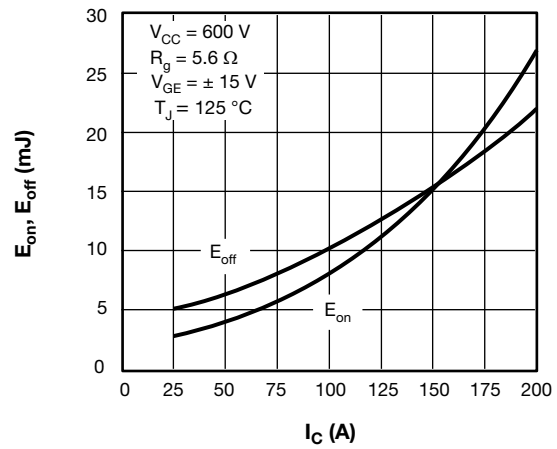


Fig. 3 - IGBT Switching Loss vs.  $I_C$

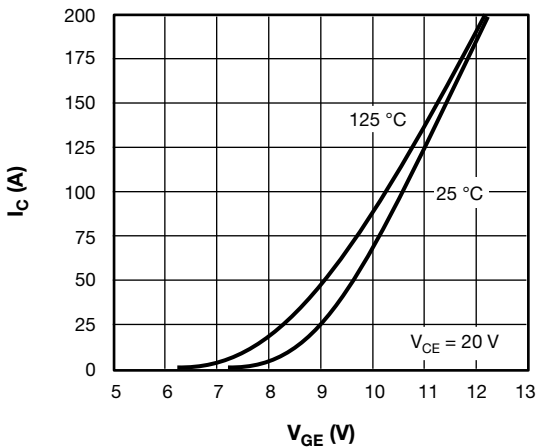


Fig. 2 - IGBT Typical Transfer Characteristics

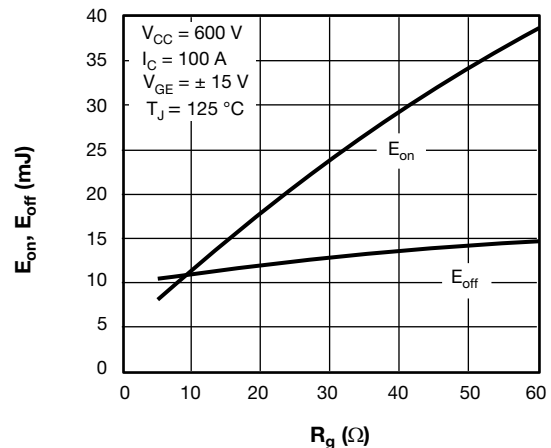


Fig. 4 - IGBT Switching Loss vs.  $R_g$

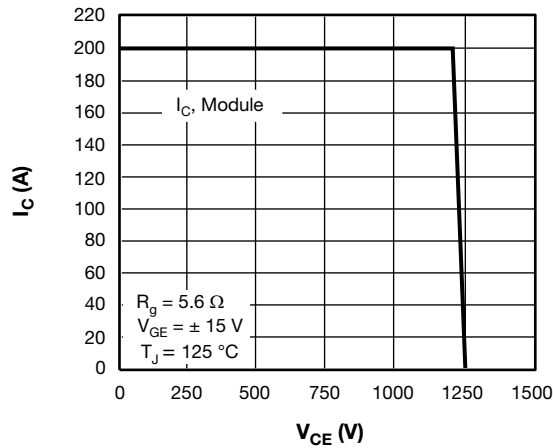


Fig. 5 - RBSOA

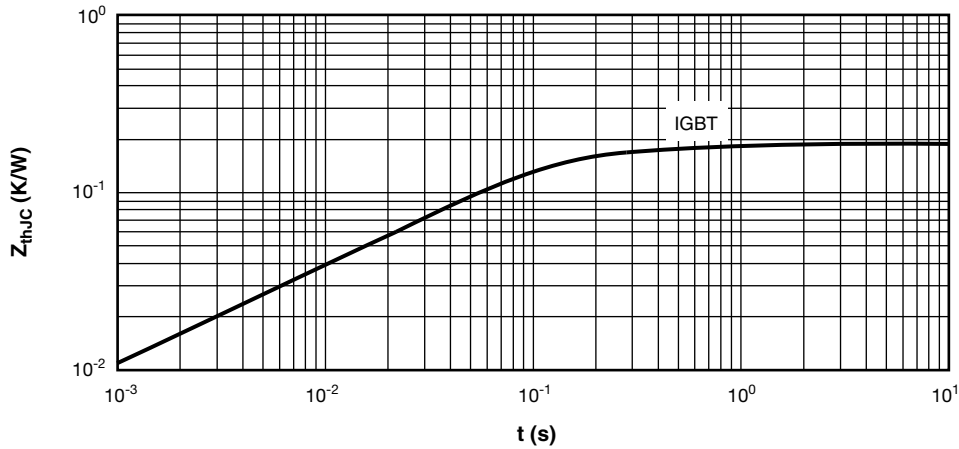


Fig. 6 - IGBT Transient Thermal Impedance

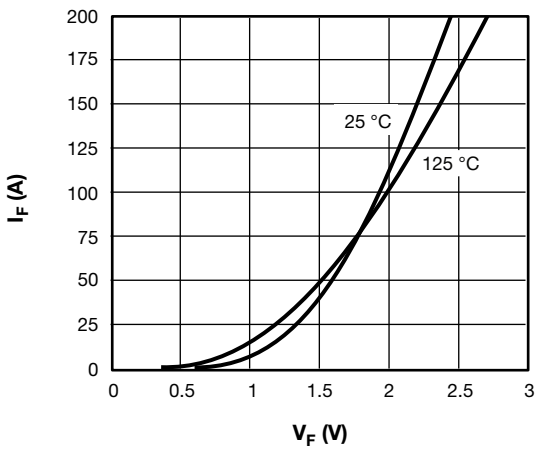


Fig. 7 - Diode Forward Characteristics

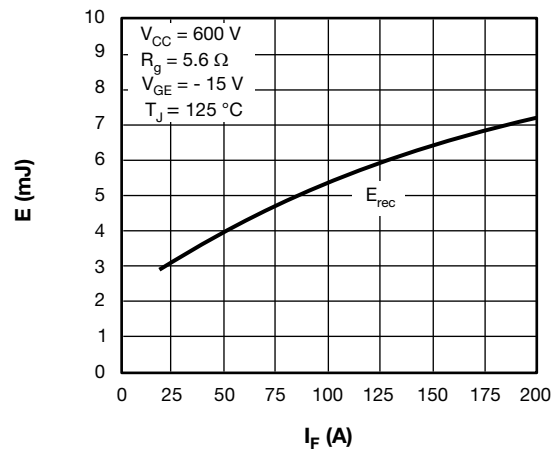


Fig. 8 - Diode Switching Loss vs.  $I_C$

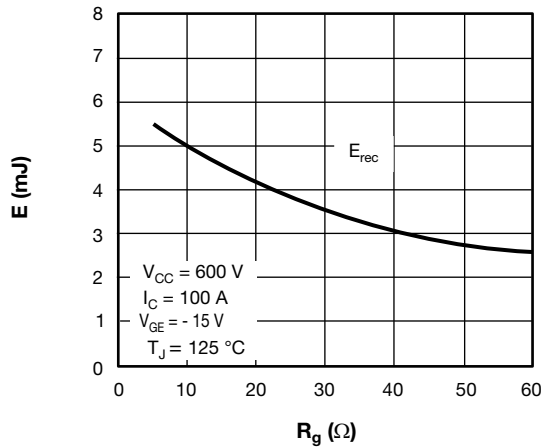


Fig. 9 - Diode Switching Loss vs.  $R_g$

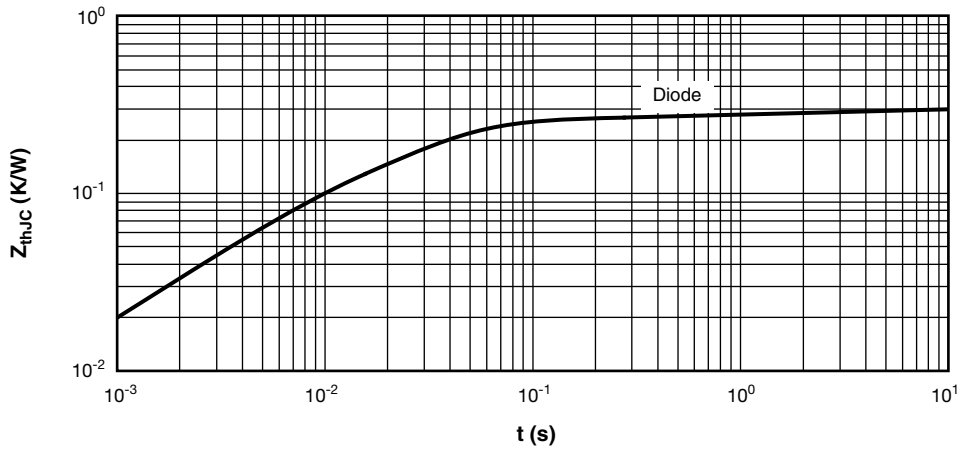
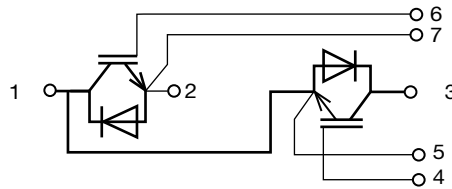


Fig. 10 - Diode Transient Thermal Impedance

**CIRCUIT CONFIGURATION**



LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95524">www.vishay.com/doc?95524</a>



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